Description

The LYQ06CA05UL is a ultra low capacitance TVS array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. It complies with IEC 61000-4-2 (ESD), ±30kV air and ±30kV contact discharge. It is assembled into a lead-free DFN1616 package. The small size, ultra low capacitance and high ESD surge protection make it an ideal choice to protect USB, cellular phones and LCD displays.

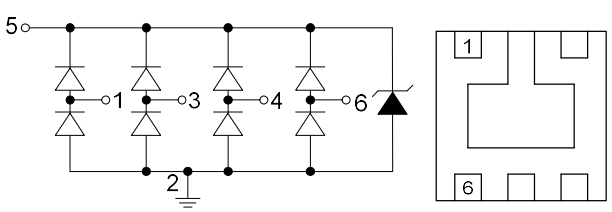
Features

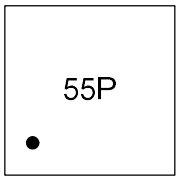
- Low clamping voltage
- Ultra low leakage current
- Operating voltage: 5V
- RoHS compliant
- IEC-61000-4-2 ESD ±30kV Air, ±30kV Contact
- Packaging: 7 inch reel, 3000pcs/reel

Applications

- Gigabit Ethernet
- USB 2.0
- MDDI Ports
- SIM Ports
- SD Card Interfaces
- Key Pads

Pin Configuration and Marking





Absolute Maximum Ratings (T_A=25℃)

Parameter	Symbol	Value
Peak Pulse Power (8/20μs)	P_{PP}	240W
Peak Pulse Current (8/20μs)	I_{PP}	11A
ESD per IEC 61000−4−2 (Air) ESD per IEC 61000−4−2 (Contact)	V_{ESD}	±30kV ±30kV
Ambient Temperature Range	T_A	−55℃ to +125℃
Storage Temperature Range	T_{STG}	−55℃ to +150℃

Electrical Characteristics (T_A=25℃)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.
Reverse Working Voltage	V_{RWM}		-	-	5V
Breakdown Voltage	V_{BR}	I_T = 1mA	6V	-	-
Reverse Leakage Current	I_R	V_{RWM} = 5V	-	-	0.1μA
Clamping Voltage	V_C	I_{PP} = 1A (8/20μs)	-	-	10V
		I_{PP} = 11A (8/20μs)	-	-	22V
Junction Capacitance	C_J	V_R = 0V, f = 1MHz, between I/O pins	-	2pF	-
		V_R = 0V, f = 1MHz, any I/O pin to ground	-	4pF	-

Typical Characteristic Curves (T_A=25℃)

Figure 1. Peak Pulse Power Rating Curve

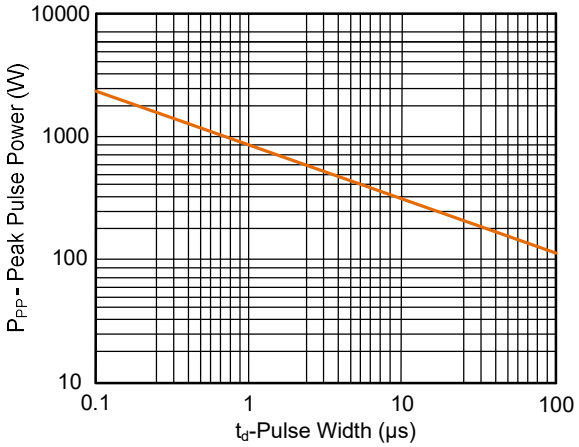


Figure 2. Pulse Derating Curve

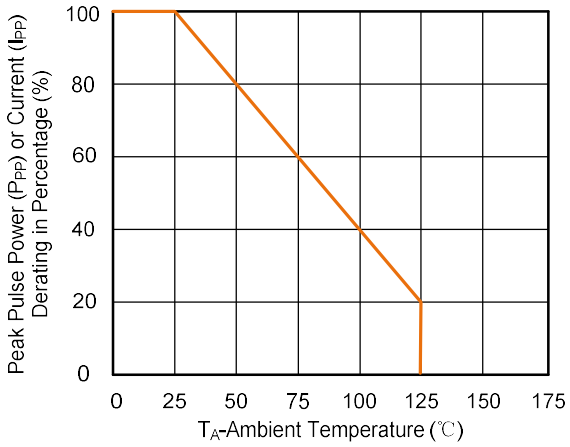


Figure 3. Clamping Voltage vs. Peak Pulse Current

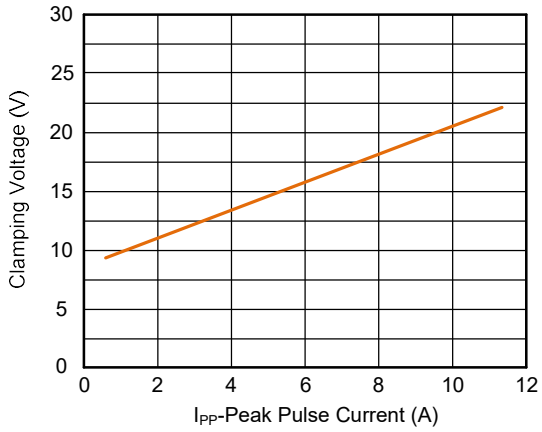


Figure 4. Junction Capacitance vs. Reverse Voltage

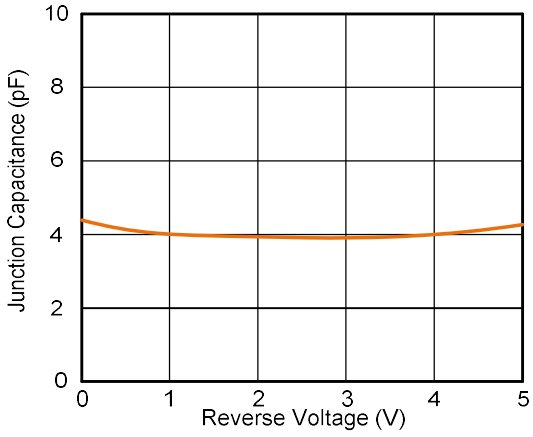


Figure 5. Pulse Waveform (8/20μs)

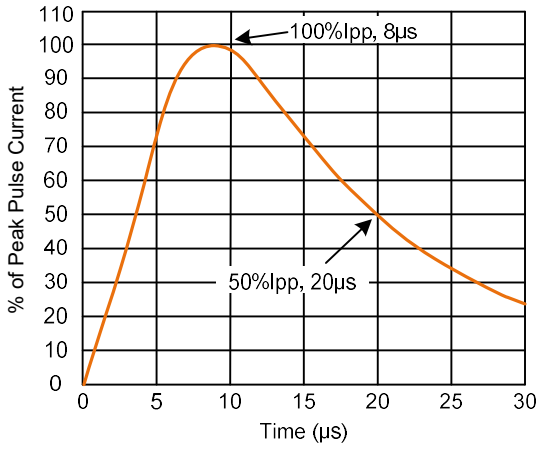
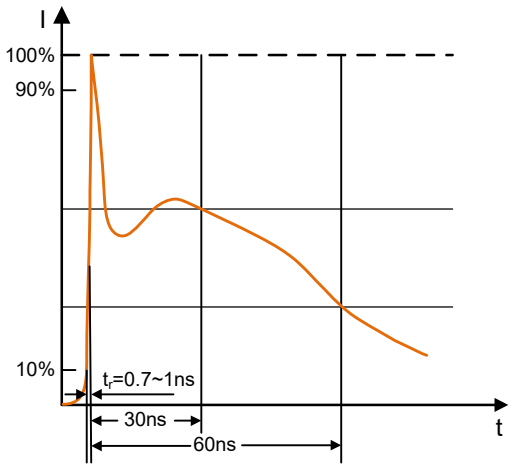
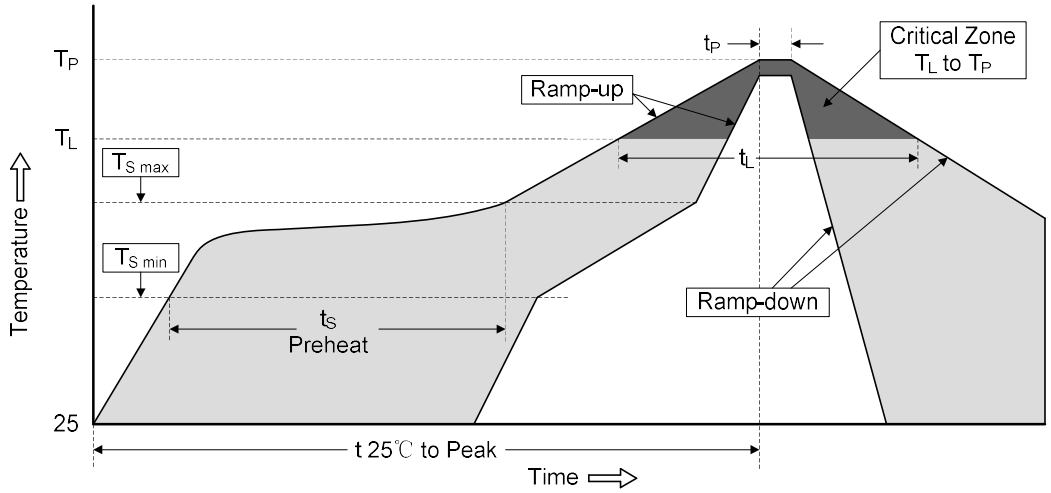


Figure 6. Pulse Waveform (IEC61000-4-2)



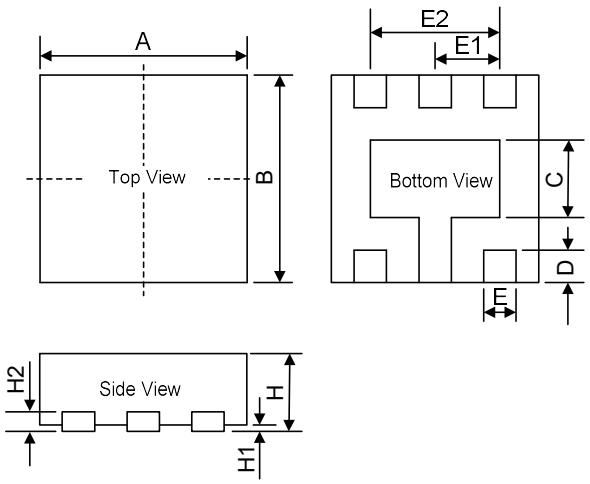
Soldering Parameters

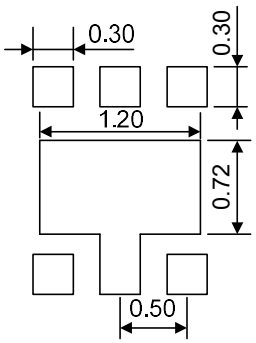
Reflow Soldering



Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

Dimensions (DFN1616)





Recommended Solder Pad Layout (mm)

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.55	1.65	0.061	0.065
B	1.55	1.65	0.061	0.065
C	0.45	0.70	0.018	0.028
D	0.20	0.30	0.008	0.012
E	0.20	0.30	0.008	0.012
E1	0.50BSC		0.020BSC	
E2	0.85	1.10	0.034	0.044
H	0.50	0.60	0.020	0.024
H1	0.00	0.05	0.000	0.002
H2	0.15REF		0.006REF	